



TECHNICAL DATA SHEET

TDS# 1517

DATE: JUNE 2013

BACON INDUSTRIES

THERMALLY CONDUCTIVE SILICONE COMPOUND SC-17

Silicone Compound SC-17 is a filled silicone-based polymer which cures to a resilient solid. It has high thermal conductivity, good thermal stability, and excellent electrical properties. It is useful in electronic applications requiring a heat conductive encapsulant. The cured compound may be knife-cut for replacement of components. New compound may be poured in place and cured to re-form a tight seal.

RECOMMENDED MIXING AND HANDLING PARAMETERS

Resin	SC-17
Activator	BA-58
Parts by weight of activator required per hundred of adhesive	2.5
Recommended potting temperature, °F	77
Working life at potting temp, hours	16
Viscosity of mixed compound at 77°F, poise	2500
Recommended cure, hr/°F	1/212 (1)

TYPICAL PROPERTIES OF CURED ADHESIVE:

Color	White
Specific Gravity	2.23
Hardness	
Shore A	74
Shore D	25
Thermal Conductivity (ASTM C518-76) at 75°F	4.2
Coefficient of Linear Thermal Expansion, (est) $10^{-6}/^{\circ}\text{F}$	60
Lap Shear Strength to Aluminum, psi	
Unprimed	200
Primed	400
Volume Resistivity, ohm-cm	8×10^{14}

NOTE:

1. Alternate cures for Silicone Compound are as follows: 4 hours at 150°F or 16 hours at 77°F.

(over)

